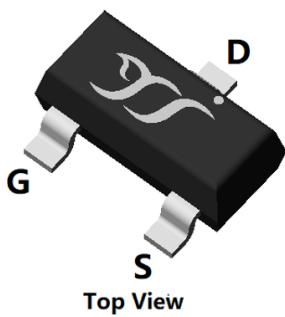
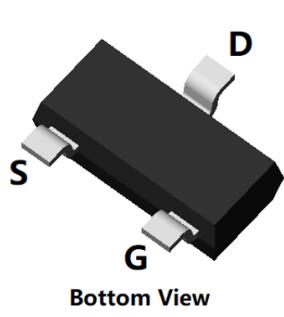


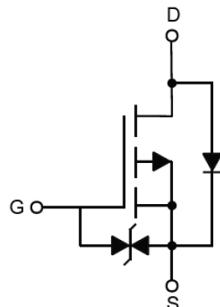
P-Channel Enhancement Mode Field Effect Transistor



Top View



Bottom View

SOT-23

Product Summary

- V_{DS} -20V
- I_D -2.4A
- $R_{DS(ON)}$ (at $V_{GS}=-4.5V$) <95mohm
- ESD Protected Up to 2.0KV (HBM)

General Description

- Trench Power LV MOSFET technology
- High Power and Current handling capability
- Low Gate Charge
- Part no. with suffix "Q" means AEC-Q101 qualified
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- PWM applications
- Power management
- Load switch

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	-20	V
Gate-source Voltage		V_{GS}	± 12	V
Drain Current	$T_A=25^\circ\text{C}$	I_D	-2.4	A
	$T_A=100^\circ\text{C}$		-1.5	
Total Power Dissipation	$T_A=25^\circ\text{C}$	P_D	890	mW
	$T_A=100^\circ\text{C}$		350	
Pulsed Drain Current ^A		I_{DM}	-10	A
Junction and Storage Temperature Range		T_J, T_{STG}	-55~+150	°C

Thermal resistance

Parameter		Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient ^B	Steady-State	$R_{\theta JA}$	115	140	°C/W

Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJL2301HQ	F2	2301H.	3000	30000	120000	7" reel



YJL2301HQ

■ Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-20			V
Zero Gate Voltage Drain Current	$I_{\text{DS}}^{\text{SS}}$	$V_{\text{DS}}=-20\text{V}, V_{\text{GS}}=0\text{V}$			-1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 12\text{V}, V_{\text{DS}}=0\text{V}$			± 10	μA
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-0.5	-1	-1.5	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-2.4\text{A}$		70	95	$\text{m}\Omega$
Diode Forward Voltage	V_{SD}	$I_{\text{S}}=-1\text{A}, V_{\text{GS}}=0\text{V}$			-1.2	V
Dynamic Parameters						
Gate resistance	R_{G}	$f=1\text{MHz}, \text{Open drain}$		15		Ω
Input Capacitance	C_{iss}	$V_{\text{DS}}=-10\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		380		pF
Output Capacitance	C_{oss}			81		
Reverse Transfer Capacitance	C_{rss}			60		
Switching Parameters						
Total Gate Charge	Q_{g}	$V_{\text{GS}}=-4.5\text{V}, V_{\text{DS}}=-10\text{V}, I_{\text{D}}=-2.4\text{A}$		5.3		nC
Gate-Source Charge	Q_{gs}			1.6		
Gate-Drain Charge	Q_{gd}			1.7		
Reverse Recovery Charge	Q_{rr}	$I_{\text{F}}=-1\text{A}, \text{di/dt}=40\text{A/us}$		1.71		ns
Reverse Recovery Time	t_{rr}			13.5		
Turn-on Delay Time	$t_{\text{D(on)}}$			8.2		
Turn-on Rise Time	t_{r}	$V_{\text{GS}}=-4.5\text{V}, V_{\text{DS}}=-10\text{V}, I_{\text{D}}=-1\text{A}$ $R_{\text{GEN}}=3\Omega$		23		ns
Turn-off Delay Time	$t_{\text{D(off)}}$			22.8		
Turn-off fall Time	t_{f}			25.6		

- A. Repetitive rating; pulse width limited by max. junction temperature.
- B. The value of $R_{\theta_{\text{JA}}}$ is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in the still air environment with $T_A=25^\circ\text{C}$. The maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design.

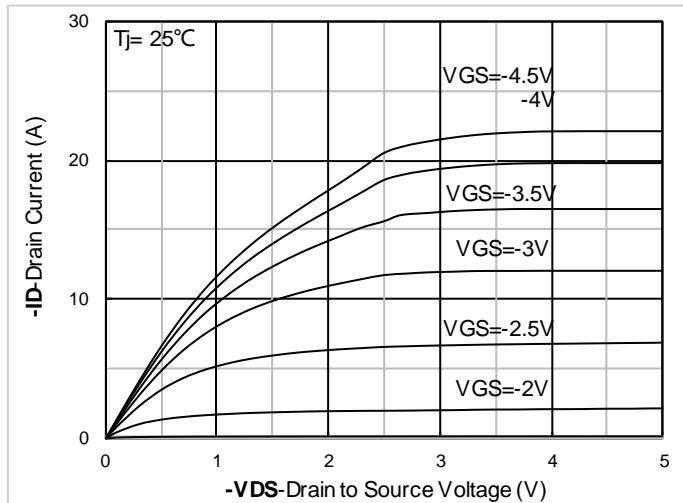
**■ Typical Performance Characteristics**

Figure1. Output Characteristics

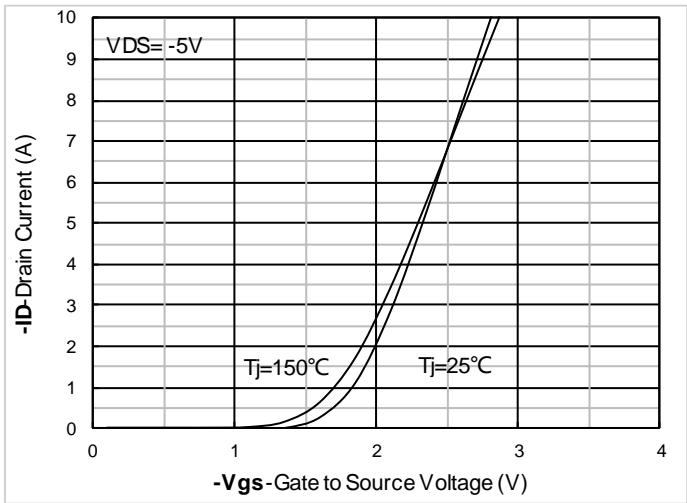


Figure2. Transfer Characteristics

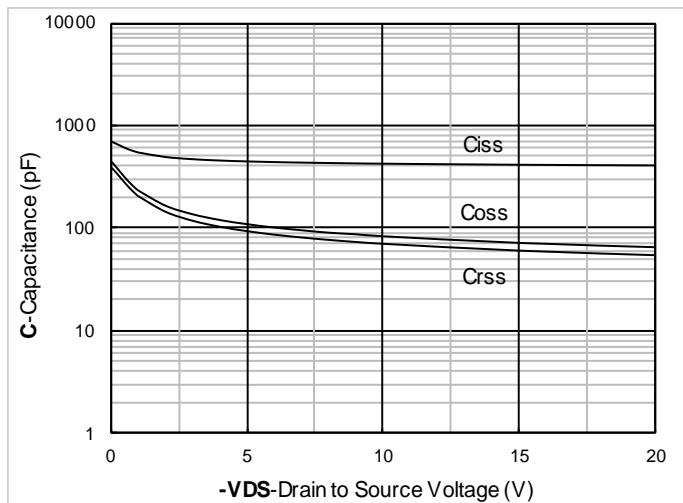


Figure3. Capacitance Characteristics

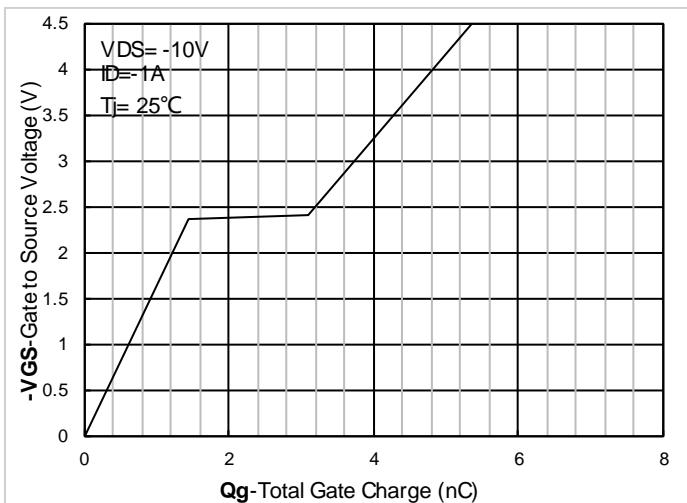


Figure4. Gate Charge

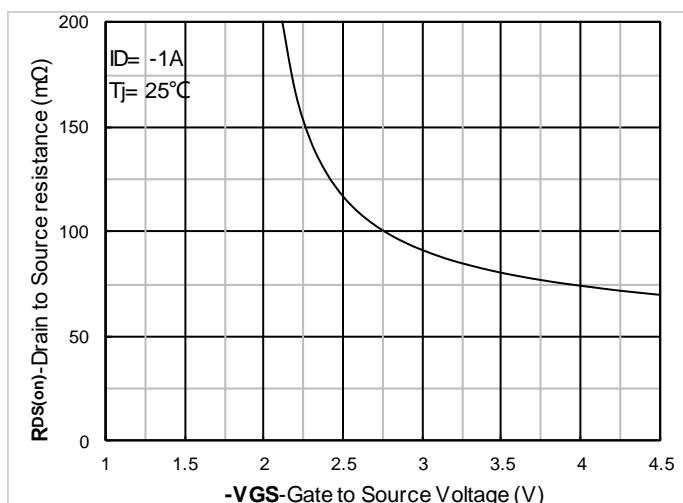


Figure5. On-Resistance vs Gate to Source Voltage

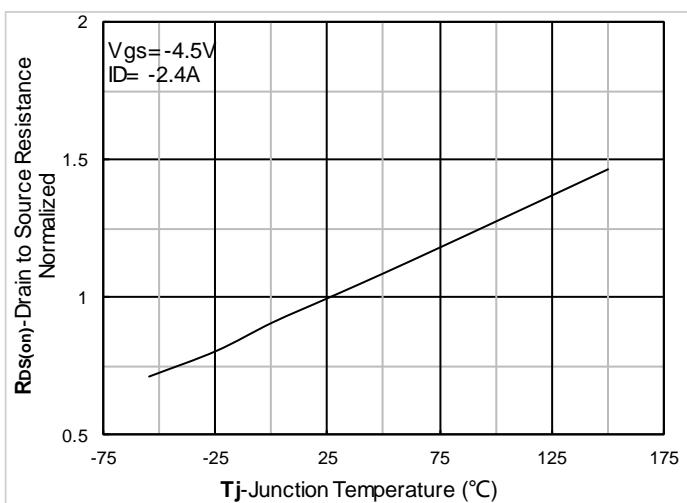


Figure6. Normalized On-Resistance

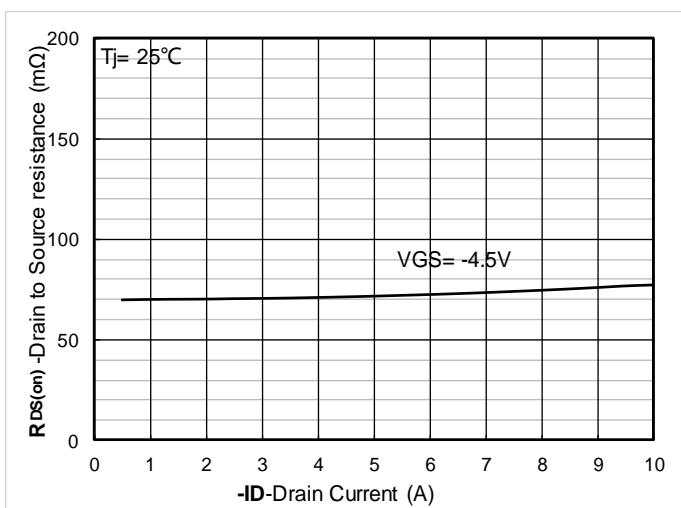
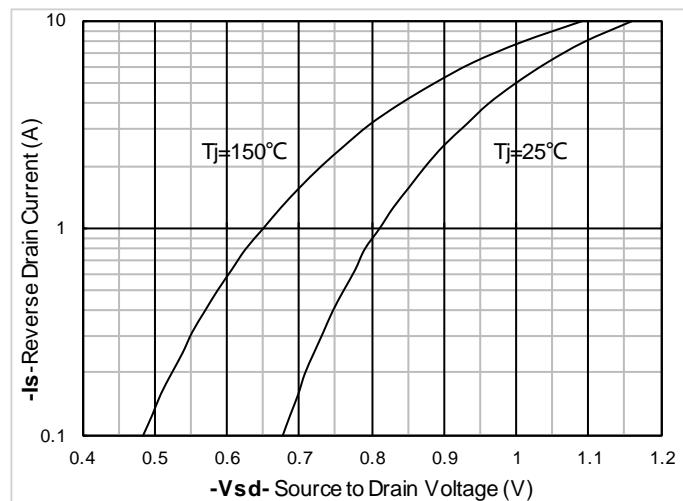
Figure 7. $R_{DS(on)}$ VS Drain Current

Figure 8. Forward characteristics of reverse diode

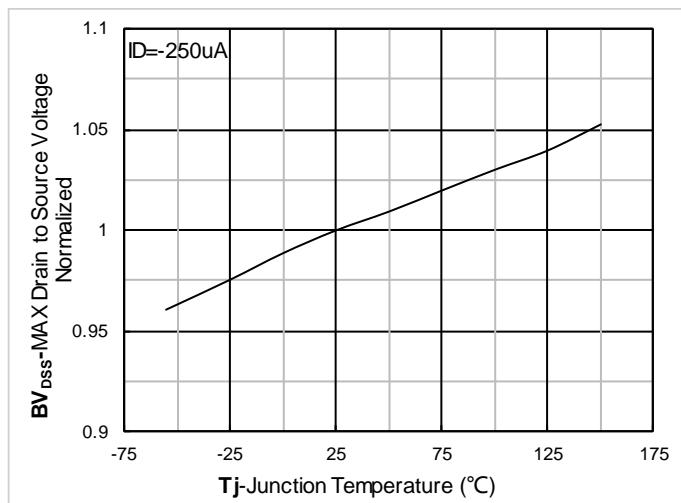


Figure 9. Normalized breakdown voltage

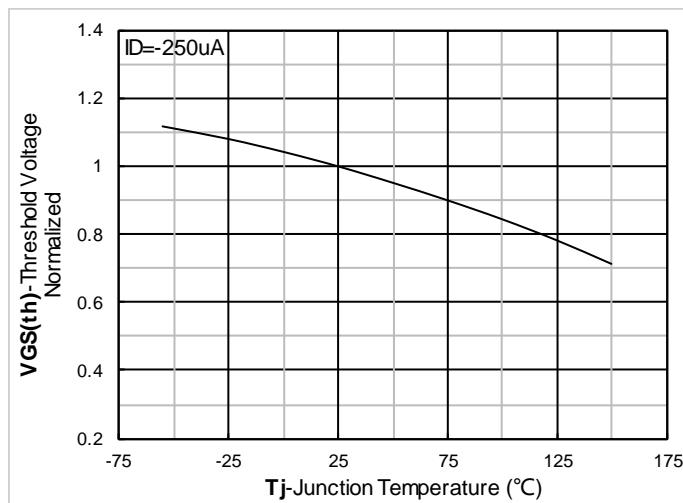


Figure 10. Normalized Threshold voltage

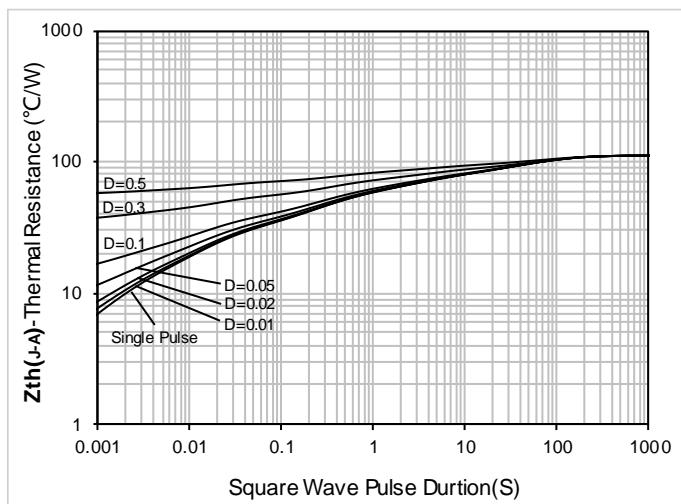


Figure 11. Maximum Transient Thermal Impedance

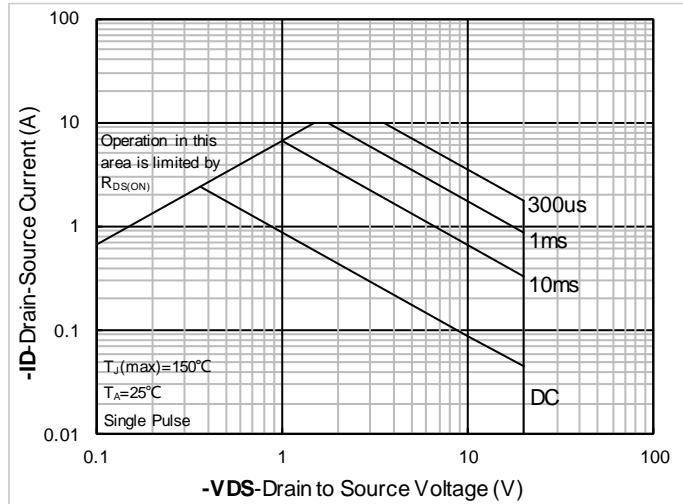
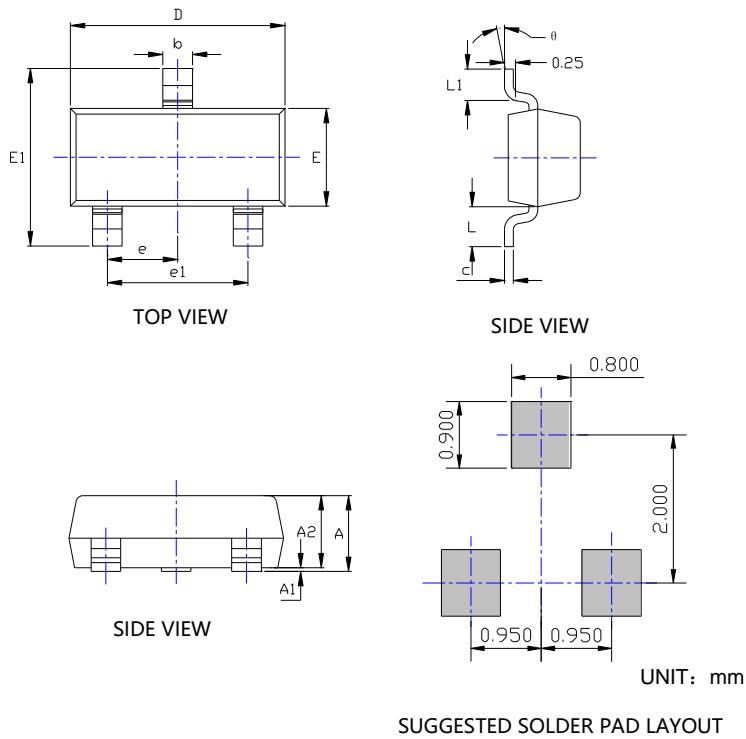


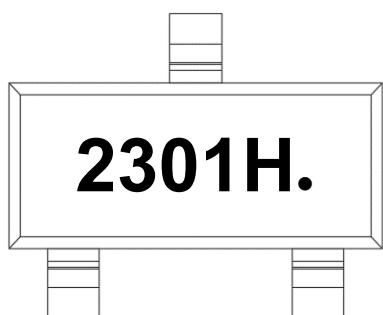
Figure 12. Safe Operation Area

**■ SOT-23 Package Outline Dimensions**

SYMBOL	INCHES		Millimeter	
	MIN.	MAX.	MIN.	MAX.
A	0.035	0.045	0.900	1.150
A1	0.000	0.004	0.000	0.100
A2	0.035	0.041	0.900	1.050
b	0.012	0.020	0.300	0.500
c	0.004	0.008	0.100	0.200
D	0.110	0.118	2.800	3.000
E	0.047	0.055	1.200	1.400
E1	0.089	0.100	2.250	2.550
e	0.037TYP		0.950TYP	
e1	0.071	0.079	1.800	2.000
L	0.022REF		0.550REF	
L1	0.012	0.020	0.300	0.500
θ	0°	8°	0°	8°

NOTE:

1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
2. TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
3. THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.

■ Marking Information

Note:

1. All marking is at middle of the product body
2. All marking is in laser marking
3. 2301H is Marking Code
4. Body color: Black



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